



#11

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/784,234
Filing Date February 14, 2001
Inventor Shozo Nagano et al.
Assignee Honeywell International, Inc.
Group Art Unit 1742
Examiner Unknown
Attorney's Docket No. 30-5000-(4015)-Div1
Title: Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating
Anodes, Metal Alloys For Use as a Conductive Interconnection in an
Integrated Circuit, and Physical Vapor Deposition Targets

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

RECEIVED

JUL 13 2001

References -- See Attached Form PTO-1449

TC 1700

The attached form PTO-1449 is submitted in compliance with
37 CFR § 1.56. Copies of the cited prior art references are attached. No
admission is made regarding whether the submitted references are prior art.

This Supplemental Information Disclosure Statement is being filed within
three months of the filing date of the application or before the mailing of a first
Office Action, whichever occurs last. Therefore, no fee is believed to be
required. However, in the event that a fee is required for filing this
Supplemental Information Disclosure Statement, please charge the fee specified
under 37 C.F.R. § 1.17(p) to Deposit Account No. 23-0925.

RECEIVED
JUN -7 2001
TC 1700 MAIL ROOM

Citation of these references is respectfully requested.

Respectfully submitted,

Dated: 6-1-01

By:
Mark S. Matkin, RECD No. 32,268

JUL 13 2001

TC 1700